

MISTRUCTURAL-GUIDED PROPERTIES AND DURABILITY OF GRANULAR/POROUS MATERIALS

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ABSTRACT

We cordially invite you to join the Minisymposium on " Microstructural-guided properties and durability of granular/porous materials" as a part of the WCCM2020 (14th. World Congress on Computational Mechanics). The conference will be held in Paris, France, during July 19-24, 2020. More details on the conference can be found at the conference webpage: [http:// www.wccm-eccomas2020.org/](http://www.wccm-eccomas2020.org/).

This Minisymposium will encompass a broad range of topics on theoretical and numerical insights into granular materials and porous materials, such as the development of discrete element method and other numerical simulations on discrete hard/soft inclusions including grains, powders, reinforced particles and pores, microstructures and mesostructures characterization of granular/porous materials, micro-/meso-structural-guided physical and mechanical properties and the durability evaluation of granular/porous materials, multiscale simulations and micromechanics theories on granular/porous materials.

We look forward to meeting you on the WCCM2020 in Paris, France.

For any further request, please contact the congress Secretariat:

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